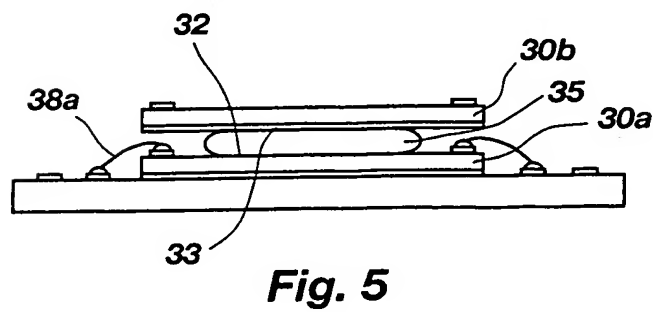
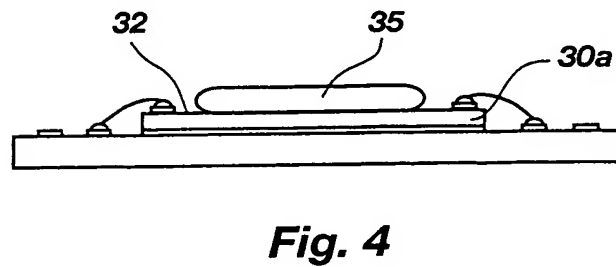
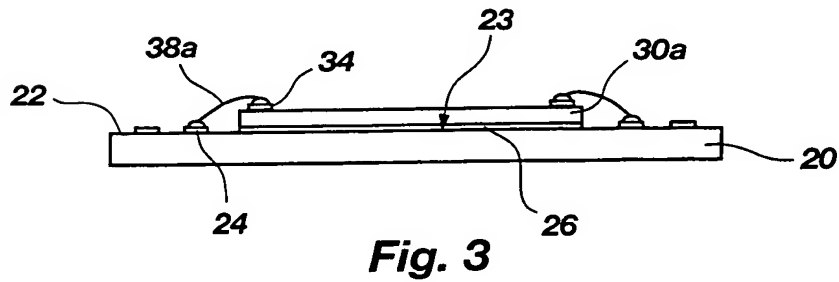
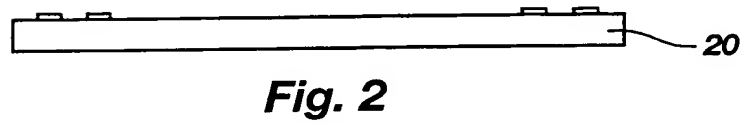
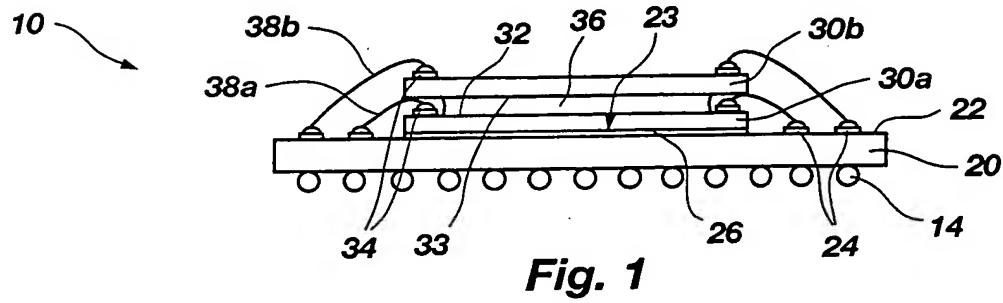


TITLE: METHODS FOR FORMING ASSEMBLIES AND PACKAGES
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SEPARATED A DISTANCE DEFINED BY ADHESIVE MATERIAL
INTERPOSED THEREBETWEEN

Inventor: J. Derderian
Docket No.: 2269-4817.3US

1/3



2/3

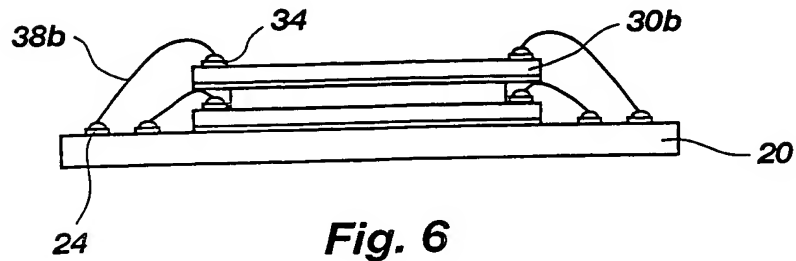


Fig. 6

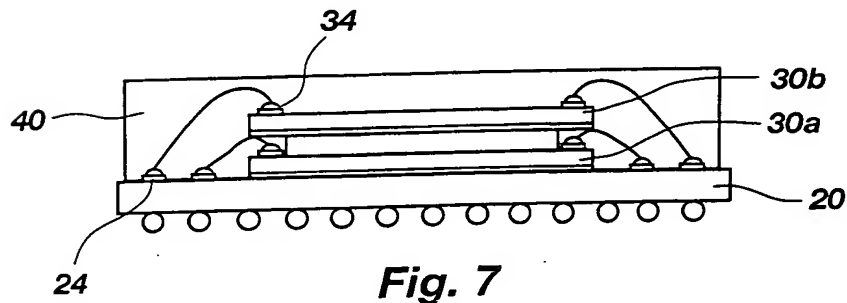


Fig. 7



Fig. 8

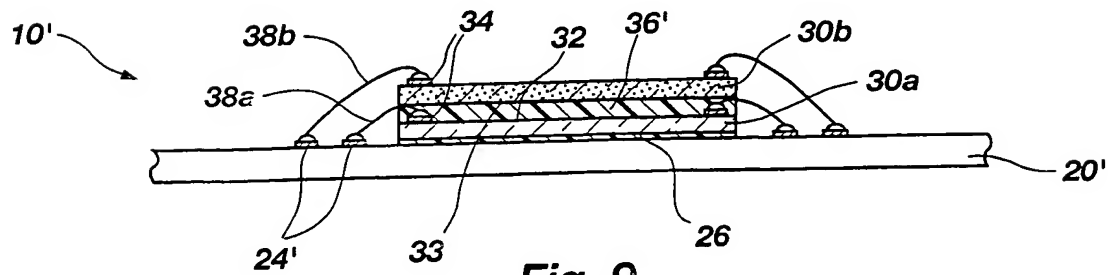


Fig. 9

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